

plastic. It is appreciated that metals, ceramic, quartz, etc. can also be used. The lift pins are metallic and the O-ring or elastomer is made from rubber. The materials selected should be compatible with the processing fluid being utilized.

In the Claims

Please cancel claims 1-16 without prejudice.

Please amend the claims as follows:

Marked-up copy of claims:

17. (Amended once) A method of processing a wafer comprising:
placing a wafer atop a wafer chuck, the chuck having a base and an upper body in which the upper body is coupled to the base by a flexible coupling that allows the upper [portion] body to tilt relative to the base;

engaging the wafer to a hollow sleeve which forms an enclosing vessel to retain a processing fluid therein, the wafer forming a floor of the vessel; and

processing the wafer utilizing the processing fluid, wherein [and in which] tilting of the wafer allows for a compliant engagement of the wafer and the sleeve [to adjust for gaps present at the engagement] to prevent or reduce leakage of the processing fluid.

18. (Not amended) The method of claim 17 further comprising the raising of at least one lift pin through the upper body to raise the wafer off of the upper body for removal of the wafer from the wafer chuck.

19. (Amended once) The method of claim [18 further comprising the] 17 wherein processing [of] the wafer [in which] includes using the processing fluid [is used] to deposit copper material onto the wafer.

20. (Amended once) The method of claim [18 further comprising the] 17 wherein processing [of] the wafer [in which] includes using the processing fluid [is used] to remove copper material from the wafer.

Clean copy of claims:

17. (Amended once) A method of processing a wafer comprising:
 placing a wafer atop a wafer chuck, the chuck having a base and an upper body in which the upper body is coupled to the base by a flexible coupling that allows the upper body to tilt relative to the base;
 engaging the wafer to a hollow sleeve which forms an enclosing vessel to retain a processing fluid therein, the wafer forming a floor of the vessel; and
 processing the wafer utilizing the processing fluid, wherein tilting of the wafer allows for a compliant engagement of the wafer and the sleeve to prevent or reduce leakage of the processing fluid.

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